

# Based Material Line Up



## WLM1/ WLM1B

### 1. CORE (C-STAGE)

Test method: 1GHz by IPC TM650-2.5.5.9, 3GHz,5GHz,10GHz by SPDR.

Thickness		ply-up	RC (%)	Dk				Df			
mm	mils			1 GHz	3 GHz	5 GHz	10 GHz	1 GHz	3 GHz	5 GHz	10 GHz
0.030	1.18	1*1027	70	4.87	6.01	5.89	5.86	0.0113	0.0168	0.0165	0.0162
0.050	1.97	1*1067	73	4.65	5.88	5.74	5.71	0.0116	0.0171	0.0168	0.0165
0.050	1.97	2*1027	66	5.16	6.18	6.09	6.06	0.0109	0.0164	0.0161	0.0158
0.065	2.56	2*1037	68	5.01	6.09	5.99	5.96	0.0111	0.0166	0.0163	0.0160
0.100	3.94	2x1078	61	5.53	6.39	6.33	6.32	0.0105	0.0159	0.0156	0.0153
0.150	5.91	3x1078	61	5.53	6.39	6.33	6.32	0.0105	0.0159	0.0156	0.0153
0.200	7.87	2x2116	56	5.90	6.61	6.58	6.58	0.0100	0.0154	0.0151	0.0148
0.300	11.81	3x2116	56	5.90	6.61	6.58	6.58	0.0100	0.0154	0.0151	0.0148
0.400	15.75	4x2116	56	5.90	6.61	6.58	6.58	0.0100	0.0154	0.0151	0.0148
0.460	18.11	2x2116+1078+2x2116	57	5.82	6.56	6.53	6.52	0.0105	0.0161	0.016	0.0151
0.500	19.69	5x2116	56	5.90	6.61	6.58	6.58	0.0100	0.0154	0.0151	0.0148
0.800	31.50	8*2116	56	5.90	6.61	6.58	6.58	0.0100	0.0154	0.0151	0.0148

# Based Material Line Up



## 2. PREPREG (B-STAGE)

Test method: 1GHz by IPC TM650-2.5.5.9, 3GHz,5GHz,10GHz by SPDR.

Glass type	RC (%) Nominal	Thickness		Dk				Df			
		mm	mils	1 GHz	3 GHz	5 GHz	10 GHz	1 GHz	3 GHz	5 GHz	10 GHz
1027	74	0.035	1.38	4.57	5.84	5.69	5.66	0.0117	0.0172	0.0169	0.0166
	77	0.040	1.57	4.35	5.71	5.54	5.50	0.0119	0.0175	0.0172	0.0169
1037	74	0.042	1.65	4.57	5.84	5.69	5.66	0.0117	0.0172	0.0169	0.0166
	77	0.048	1.89	4.35	5.71	5.54	5.50	0.0119	0.0175	0.0172	0.0169
1078	71	0.075	2.95	4.79	5.97	5.84	5.81	0.0114	0.0169	0.0166	0.0163
2116	62	0.120	4.72	5.45	6.35	6.28	6.27	0.0106	0.0160	0.0157	0.0154

## 3. REMARK

- 1) All the values listed above are for your reference only. Please contact Shengyi Technology Co., Ltd. for detailed information. All rights from this line up are reserved by Shengyi Technology Co., Ltd.
- 2) Last update: Feb. 2022.